

10 than said width dimension , and,
11 said second portion of said interface having a contacting area approximating the contacting
12 area of said conductive joint members of said first portion and ~~operable~~ so positioned to
13 accommodate expansion mismatch stresses in said conductive joint members.

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1 1. In an array of conductive joints between signal pads on a surface of an integrated circuit
2 member of a material having a first thermal responsiveness and corresponding
3 contacts on an aligned wiring support member of a material having a second thermal
4 responsiveness,
5 the improvement comprising:
6 an interface having first and second portions,
7 said first portion of said interface containing an array of elongated conductive joint
8 members each having a contacting area made up of a length contacting dimension and
9 a width contacting dimension and with said length contacting dimension being longer
10 than said width dimension , and,
11 said second portion of said interface having a contacting area approximating the contacting
12 area of said conductive joint members of said first portion and so positioned to
13 accommodate expansion mismatch stresses in said conductive joint members.

Claim 2 is to be amended by erasing on line 2 the cross hatched word "common" and replacing it
with the underlined word - aligned- as follows.

1 2. The improvement of claim 1 wherein said second portion of said interface is at least one
2 contacting area positioned orthogonally with respect to said ~~common~~ aligned direction.

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- A2
- 1 2. The improvement of claim 1 wherein said second portion of said interface is at least one
 - 2 contacting area positioned orthogonally with respect to said aligned direction.

Claim 7 is to be amended by erasing on line 14 the cross hatched words "oriented in " and replacing it with the underlined expression - so positioned- ; and on line 15 erase the cross hatched expression " a direction operable"- and correct the line numbering as follows.

- 1 7. An improvement in an array of conductive joints between pads on a surface of an
- 2 integrated circuit member of a material having a first thermal expansion responsiveness and
- 3 corresponding contacts on an aligned wiring support member of a material having a second
- 4 thermal responsiveness,
- 5 comprising in combination:
- 6 an interface between said pads and said contacts, having first and second portions,
- 7 said first portion of said interface containing an array of elongated conductive joint
- 8 members each having a contacting area made up of a length contacting dimension and
- 9 a width contacting dimension and with said length contacting dimension being longer
- 10 than said width dimension,
- 11 said array of conductive joint members each being oriented with said length contacting
- 12 length dimension in a common direction, and,
- 13 ~~13~~ 13 said second portion of said interface having a contacting area approximating the contacting
- 14 ~~14~~ 14 area of said conductive joint members of said first portion and ~~oriented in~~ so positioned,
- 15 ~~15 a direction operable~~ to accommodate expansion mismatch stresses in said
- 16 ~~16~~ 16 conductive joint members.

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1 7. An improvement in an array of conductive joints between pads on a surface of an
2 integrated circuit member of a material having a first thermal expansion responsiveness and
3 corresponding contacts on an aligned wiring support member of a material having a second
4 thermal responsiveness,
5 comprising in combination:
6 an interface between said pads and said contacts, having first and second portions,
7 said first portion of said interface containing an array of elongated conductive joint
8 members each having a contacting area made up of a length contacting dimension and
9 a width contacting dimension and with said length contacting dimension being longer
10 than said width dimension,
11 said array of conductive joint members each being oriented with said length contacting
12 length dimension in a common direction, and,
13 said second portion of said interface having a contacting area approximating the contacting
14 area of said conductive joint members of said first portion and so positioned
15 to accommodate expansion mismatch stresses in said
16 conductive joint members.

REMARKS

In the 5/9/02 office action there is an objection to the drawings, an interpretation indicating a need for clarification of functional claim language accompanied by a 35USC112 rejection and three separate 35USC102 rejections on three references. The topics are addressed in the order of the enumerated items in the office action.